

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2020/0294956 A1 Hartmann et al.

Sep. 17, 2020 (43) **Pub. Date:**

(54) ARRANGEMENT AND METHOD FOR JOINING AT LEAST TWO JOINING **PARTNERS**

(71) Applicant: Infineon Technologies AG, Neubiberg

Inventors: Steffen Hartmann, Bad Sassendorf (DE); Roland Speckels, Kamen (DE)

Appl. No.: 16/806,844 (21)

Filed: (22)Mar. 2, 2020

(30)Foreign Application Priority Data

Mar. 12, 2019 (EP) 19162070.7

Publication Classification

(51) **Int. Cl.** H01L 23/00 (2006.01)

(52) U.S. Cl.

CPC H01L 24/75 (2013.01); H01L 24/83 (2013.01); H01L 2224/7565 (2013.01); H01L 2224/75252 (2013.01); H01L 2224/83203 (2013.01); H01L 2224/32225 (2013.01); H01L 2224/83053 (2013.01); H01L 2224/8384 (2013.01); H01L 2224/75301 (2013.01); H01L 2224/7555 (2013.01); H01L 24/32 (2013.01); H01L 2224/75821 (2013.01)

ABSTRACT (57)

An arrangement for joining two joining members includes a first part having a support surface, a first carrier element configured to carry at least one foil, a transportation unit configured to arrange the first carrier element such that the foil is arranged above the support surface in a vertical direction, and a second part configured to exert pressure to a joining stack, when the joining stack is arranged on the support surface. The joining stack includes a first joining member arranged on the support surface, a second joining member, and an electrically conductive connection layer arranged between the joining members. When pressure is exerted to the joining stack, the foil is arranged between the second part and the joining stack and is pressed onto the joining stack and the joining stack is pressed onto the first part, compressing the connection layer and forming a substance-to-substance bond between the joining members.

